Rui Zhang

List of Publications by Year
in descending order

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15	557	933447 10	1372567 10
papers	citations	h-index	g-index

15	15	15	917
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Mechanical Properties of Atomically Thin Tungsten Dichalcogenides: WS₂, WSe₂, and WTe₂. ACS Nano, 2021, 15, 2600-2610.	14.6	65
2	Controlled Layer Thinning and pâ€Type Doping of WSe₂ by Vapor XeF₂. Advanced Functional Materials, 2017, 27, 1702455.	14.9	103
3	Degradation behaviors of micro ball grid array (Î¼BGA) solder joints under the coupled effects of electromigration and thermal stress. Journal of Materials Science: Materials in Electronics, 2016, 27, 11583-11592.	2.2	17
4	Elastic properties of suspended multilayer WSe2. Applied Physics Letters, 2016, 108, .	3.3	121
5	Optical lithography technique for the fabrication of devices from mechanically exfoliated two-dimensional materials. Microelectronic Engineering, 2016, 154, 62-68.	2.4	11
6	Tunable MEMS cantilever resonators electrothermally actuated and piezoelectrically sensed. Microelectronic Engineering, 2015, 145, 38-42.	2.4	12
7	Electromigration-induced intermetallic growth and voids formation in symmetrical Cu/Sn/Cu and Cu/Intermetallic compounds (IMCs)/Cu joints. Journal of Materials Science: Materials in Electronics, 2015, 26, 2674-2681.	2.2	27
8	Rapid formation of Cu-Sn intermetallic compounds by strong electric current. , 2014, , .		1
9	Relationship between morphologies and orientations of Cu6Sn5 grains in Sn3.0Ag0.5Cu solder joints on different Cu pads. Materials Characterization, 2014, 88, 58-68.	4.4	63
10	Phase transformation and grain orientation of Cuâ€“Sn intermetallic compounds during low temperature bonding process. Journal of Materials Science: Materials in Electronics, 2013, 24, 3905-3913.	2.2	52
11	Formation mechanism and orientation of Cu3Sn grains in Cuâ€“Sn intermetallic compound joints. Materials Letters, 2013, 110, 137-140.	2.6	74
12	Effect of high temperature thermal aging on microstructural evolution of Sn3Ag0.5Cu/Cu solder joints. , 2013, , .		0
13	Electromigration failure of SnAgCu lead-free BGA package assembled with SnPb solder paste. , 2013, , .		1
14	Growth mechanism of Cu-Sn full IMC joints on polycrystalline and single crystal Cu substrate. , 2013, , .		0
15	Mechanical Properties and Applications of Two-Dimensional Materials. , 0, , .		10